

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Michael S. Leung et al.

Confirmation No.: 8955

Serial No.: 10/666,399

Examiner: Abul Kalam

Filed: September 18, 2003

Art Unit: 2814

Title: MOLDED CHIP FABRICATION METHOD

Notice of Allowance Date: October 14, 2010

Mail Stop Issue Fee
Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450


COMMENTS ON STATEMENT OF REASONS FOR ALLOWANCE

Sir:

Applicants agree that the Examiner has accurately stated one or more reasons for allowance of the claims. However, the claims may include other patentable aspects that were not identified by the Examiner. This response is submitted to avoid the possibility of any unnecessary limitation on the scope of the claims which might result from the stated reason for allowance. It is being submitted concurrently with the issue fee payment.

Respectfully submitted,

Dated: 1/10/11


Jaye G. Heybl
Registration No. 42,661
Attorney for Applicants

KOPPEL, PATRICK, HEYBL & DAWSON
2815 Townsgate Road, Suite 215
Westlake Village, California 91361
(805) 373-0060

J\11\PO298US-7\011011\ReasonsForAllowance

CERTIFICATE OF ELECTRONIC FILING

I hereby certify that this correspondence is being deposited with the United States Patent & Trademark office via Electronic Filing through the United States Patent and Trademark Office e-business website, on the date shown below.

1/10/11
Date


Joan Harriman